


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	MDG/24/14645	
<b>1.3 Title of PCN</b>	ASE Kaohsiung (Taiwan) FBGA package copper palladium bonding wire introduction on STM32H72/73x, STM32H74/75x and STM32U5x listed products.	
<b>1.4 Product Category</b>	STM32H72x, STM32H73x, STM32H74x, STM32H75x, and STM32U5x	
<b>1.5 Issue date</b>	2024-05-16	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	KRAUSE INA
<b>2.1.2 Phone</b>	+49 89460062370
<b>2.1.3 Email</b>	ina.krause@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Ricardo Antonio DE SA EARP
<b>2.1.2 Marketing Manager</b>	Veronique BARLATIER
<b>2.1.3 Quality Manager</b>	Pascal NARCHE

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Materials	Direct Material: Bond Wire - Metallurgy (metallic composition/ raw material)	ASE Kaohsiung (Taiwan)

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	Assembly lines / wire bonding: - AMKOR (Philippines) / Gold wire - ASE Kaohsiung (Taiwan) / Gold wire	Assembly lines / wire bonding: - AMKOR (Philippines) / Gold wire - ASE Kaohsiung (Taiwan) / Gold wire - ASE Kaohsiung (Taiwan) / Copper Palladium wire - Additional Source
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	no impact on form, Fit, Function	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	To improve service
<b>5.2 Customer Benefit</b>	SERVICE IMPROVEMENT

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	traceability ensured by ST Internal tools
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2024-05-06
<b>7.2 Intended start of delivery</b>	2024-06-05
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	14645 MDG-MCD-RER2021 V3.0 - PCN12916 - PCN14645 - ASE KH xFBGA package - Reliability Evaluation Report.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2024-05-16

**9. Attachments (additional documentations)**

14645 Public product.pdf  
 14645 MDG-MCD-RER2021 V3.0 - PCN12916 - PCN14645 - ASE KH xFBGA package - Reliability Evaluation Report.pdf  
 14645 PCN14645\_Additional information.pdf

**10. Affected parts**

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
3576971	STM32H725AGI6	
3576968	STM32H725IGK6	
3576972	STM32H730ABI6Q	
3576969	STM32H730IBK6Q	
3576970	STM32H735IGK6	
2980957	STM32H750XBH6	
2851001	STM32H753XIH6	
	STM32H755XIH6	
3515805	STM32H757XIH6	
	STM32U535VEI6Q	
	STM32U545REI6	
	STM32U545REI6Q	
	STM32U545VEI6Q	
	STM32U585QII3	
	STM32U595AJH6	
	STM32U595AJH6Q	
	STM32U595QJI6	
	STM32U595QJI6Q	
	STM32U599NJH6Q	
	STM32U5A5AJH6	
	STM32U5A5AJH6Q	
	STM32U5A5QJI6	
	STM32U5A5QJI6Q	
	STM32U5A9NJH6Q	
	STM32U5G9NJH6Q	
	STM32U5G9ZJJ6Q	

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